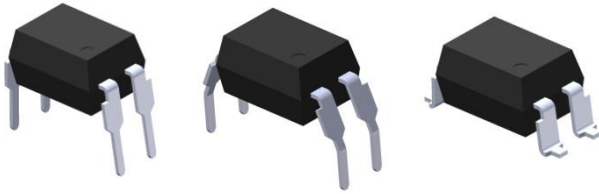
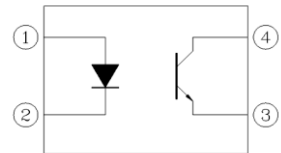




4 PIN DIP PHOTOTRANSISTOR PHOTOCOUPLER GX817 Series



Schematic



Pin Configuration

1. Anode
2. Cathode
3. Emitter
4. Collector

Features:

- Compliance Halogens Free (Only copper leadframe)
(Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)
- Current transfer ratio
(CTR: 50~600% at $I_F = 5\text{mA}$, $V_{CE} = 5\text{V}$)
- High isolation voltage between input and output (Viso = 5000Vrms)
- Creepage distance > 7.62mm
- Operating temperature up to +110°C
- Compact small outline package
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- UL and cUL approved(No.E214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CQC approved

Description

The GX817series of devices each consist of an infrared emitting diodes, optically coupled to a phototransistor detector.

They are packaged in a 4-pin DIP package and available in wide-lead spacing and SMD option.

Applications

- Programmable controllers
- System appliances, measuring instruments
- Telecommunication equipments
- Home appliances, such as fan heaters, etc.
- Signal transmission between circuits of different potentials and impedances

**Absolute Maximum Ratings (Ta=25°C)**

	Parameter	Symbol	Rating	Unit
Input	Forward current	I_F	60	mA
	Peak forward current (1us, pulse)	I_{FP}	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P_D	100	mW
	Derating factor (above $T_a = 100^\circ\text{C}$)		2.9	mW/°C
Output	Power dissipation	P_C	150	mW
	Derating factor (above $T_a = 100^\circ\text{C}$)		5.8	mW/°C
	Collector current	I_C	50	mA
	Collector-Emitter voltage	V_{CEO}	35	V
	Emitter-Collector voltage	V_{ECO}	6	V
Total Power Dissipation	P_{TOT}	200	mW	
Isolation Voltage* ¹	V_{ISO}	5000	V rms	
Operating Temperature	T_{OPR}	-55 to 110	°C	
Storage Temperature	T_{STG}	-55 to 125	°C	
Soldering Temperature* ²	T_{SOL}	260	°C	

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2 are shorted together, and pins 3, 4 are shorted together.

*2 For 10 seconds



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Guo Xin Jia Pin SEMICONDUCTOR

GX817

Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Voltage	V_F	-	1.2	1.4	V	$I_F = 20\text{mA}$
Reverse Current	I_R	-	-	10	μA	$V_R = 4\text{V}$
Input capacitance	C_{in}	-	30	250	pF	$V = 0, f = 1\text{kHz}$

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Collector-Emitter dark current	I_{CEO}	-	-	100	nA	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$
Collector-Emitter breakdown voltage	BV_{CEO}	35	-	-	V	$I_C = 0.1\text{mA}$
Emitter-Collector breakdown voltage	BV_{ECO}	6	-	-	V	$I_E = 0.1\text{mA}$

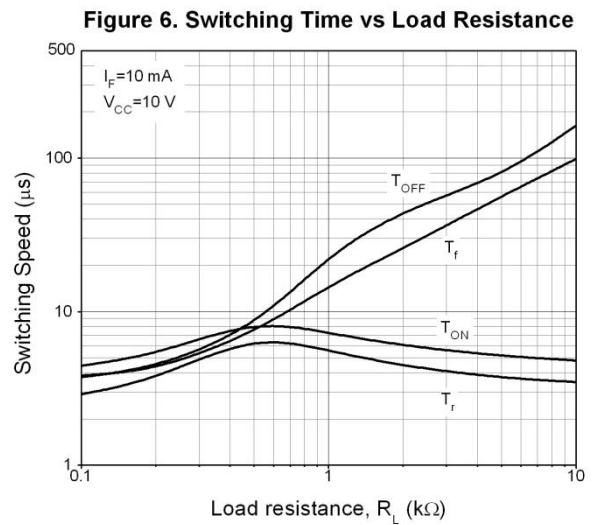
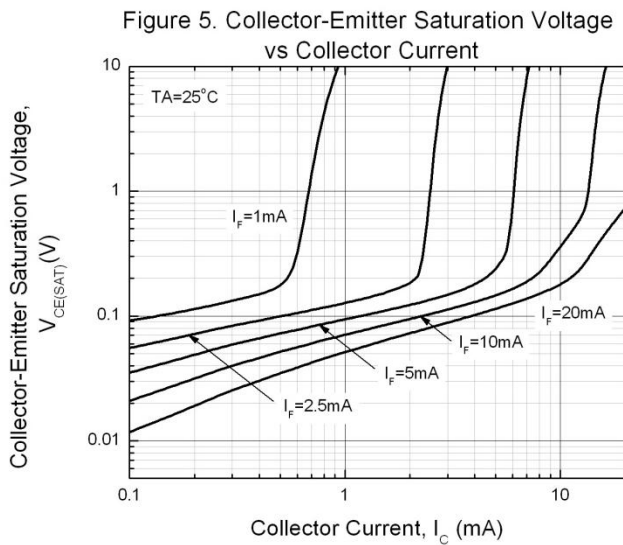
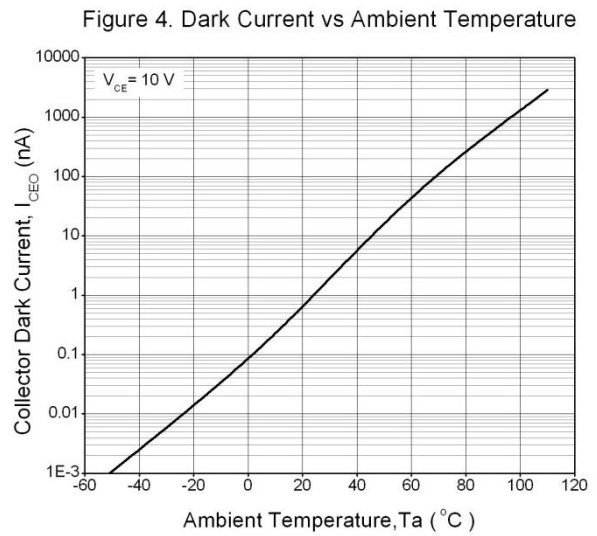
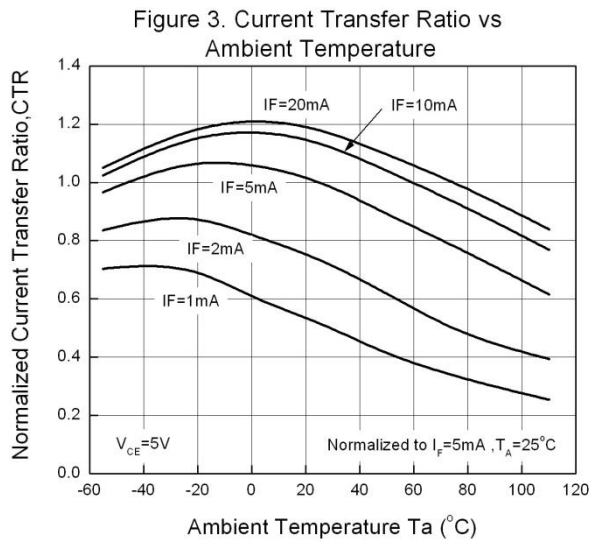
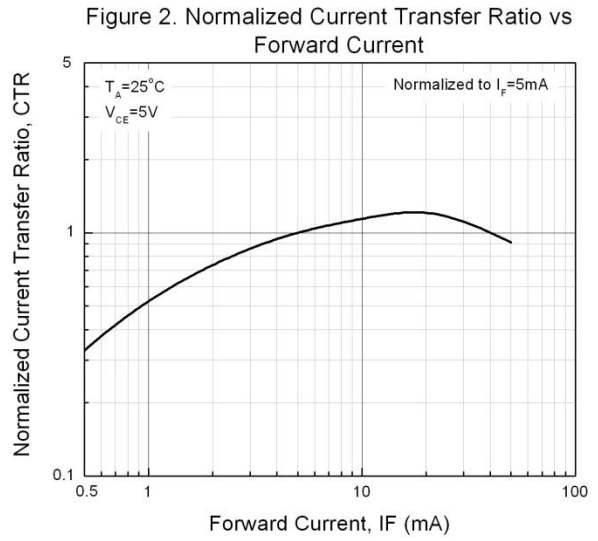
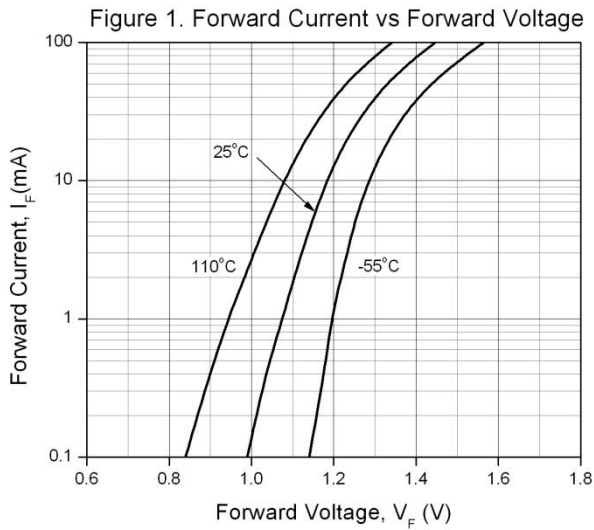
Transfer Characteristics

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer ratio	GX817	50	-	600	%	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$
	GX817A	80	-	160		
	GX817B	130	-	260		
	GX817C	200	-	400		
	GX817D	300	-	600		
	GX817X	100	-	200		
	GX817Y	150	-	300		
Collector-Emitter saturation voltage	$V_{CE(sat)}$	-	0.1	0.2	V	$I_F = 20\text{mA}, I_C = 1\text{mA}$
Isolation resistance	R_{IO}	5×10^{10}	-	-	Ω	$V_{IO} = 500\text{Vdc}, 40\sim 60\% \text{ R.H.}$
Floating capacitance	C_{IO}	-	0.6	1.0	pF	$V_{IO} = 0, f = 1\text{MHz}$
Cut-off frequency	f_c	-	80	-	kHz	$V_{CE} = 5\text{V}, I_C = 2\text{mA}, R_L = 100\Omega, -3\text{dB}$
Rise time	t_r	-	-	18	μs	$V_{CE} = 2\text{V}, I_C = 2\text{mA}, R_L = 100\Omega$
Fall time	t_f	-	-	18	μs	

* Typical values at $T_a = 25^\circ\text{C}$



Typical Electro-Optical Characteristics Curves



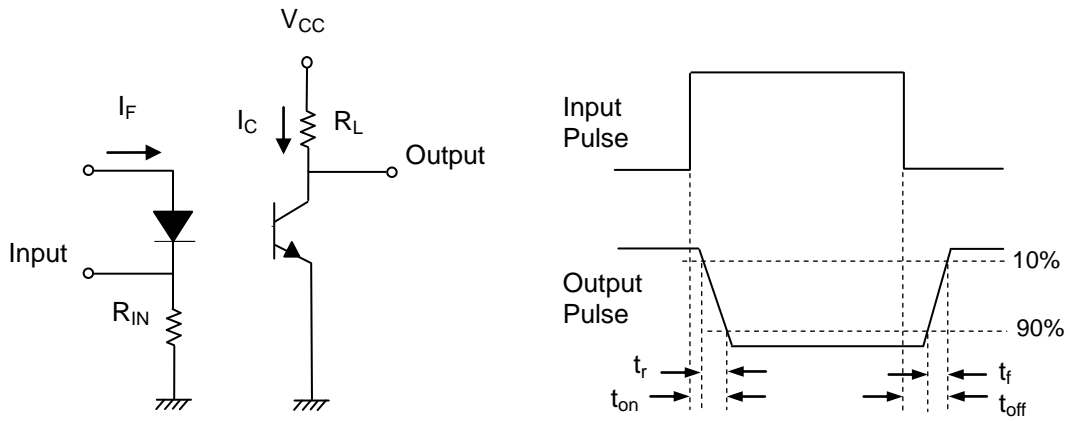


Figure 7. Switching Time Test Circuit & Waveforms



Order Information

Part Number

GX817X(Y)(Z)-FV

Note

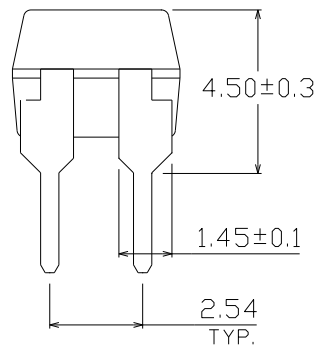
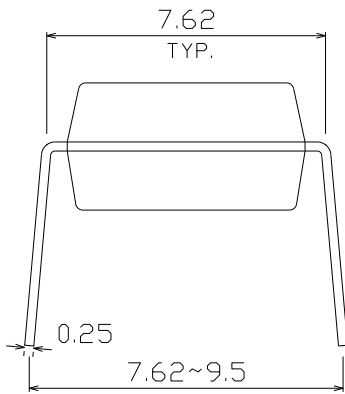
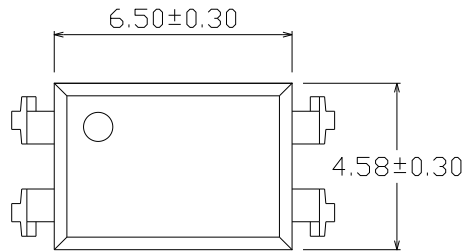
- X = Lead form option (S1, S2, M or none)
- Y = CTR Rank (A, B, C, D, X, Y or none)
- Z = Tape and reel option (TU, TD or none)
- F = Lead frame option (F: Iron, None: copper)
- V = VDE safety (optional)

Option	Description	Packing quantity
None	Standard DIP-4	100 units per tube
M	Wide lead bend (0.4 inch spacing)	100 units per tube
S1 (TU)	Surface mount lead form (low profile) + TU tape & reel option	1500 units per reel
S1 (TD)	Surface mount lead form (low profile) + TD tape & reel option	1500 units per reel
S2 (TU)	Surface mount lead form (low profile) + TU tape & reel option	2000 units per reel
S2 (TD)	Surface mount lead form (low profile) + TD tape & reel option	2000 units per reel

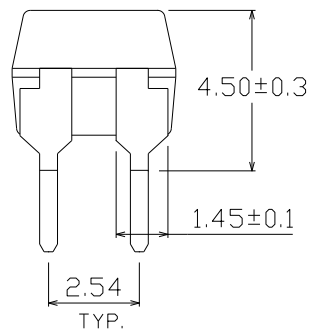
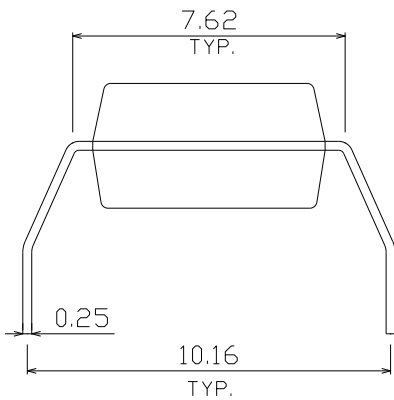
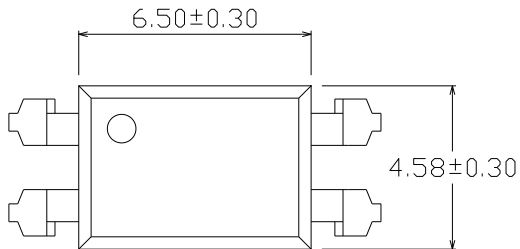


Package Dimension (Dimensions in mm)

Standard DIP Type

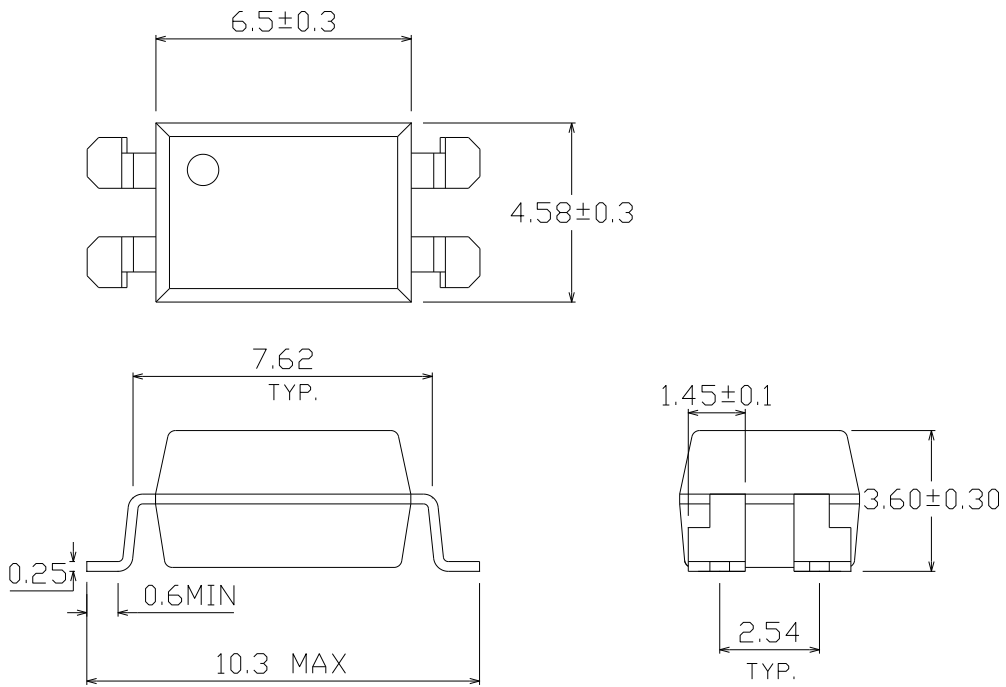


Option M Type

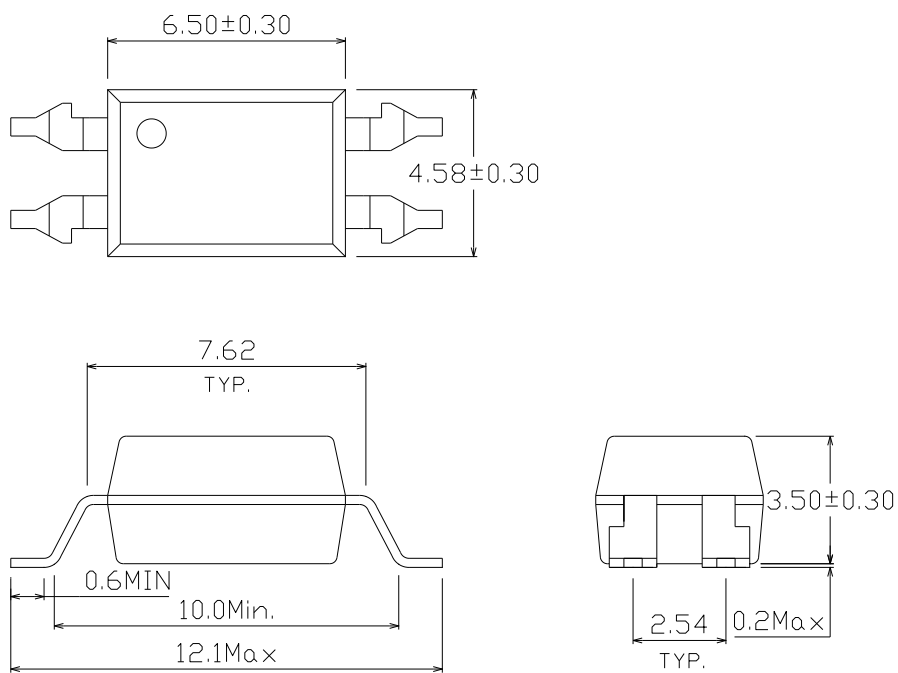




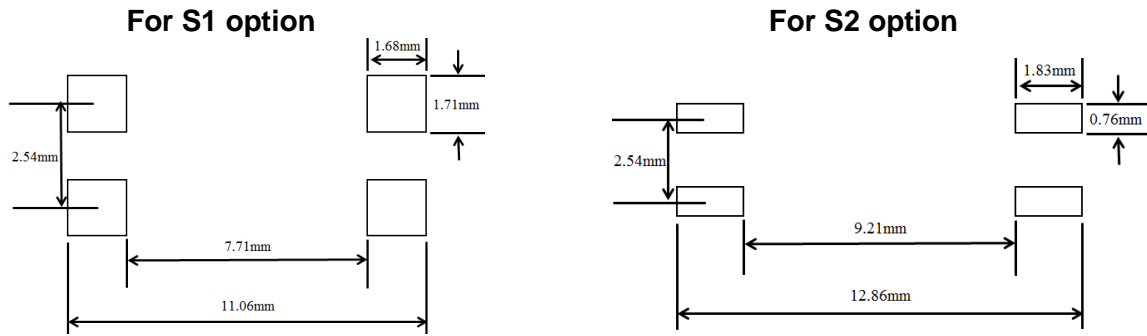
Option S1 Type



Option S2 Type



Recommended pad layout for surface mount leadform



Notes

Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.



Device Marking

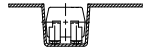
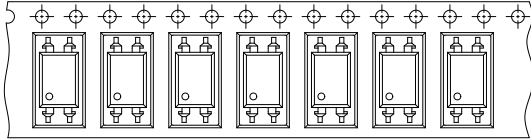


Notes

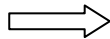
817	denotes Device Number
F	denotes Factory Code (G: China and Green part)
R	denotes CTR Rank (A, B, C, D, X, Y or none)
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
V	denotes VDE (optional)

Tape & Reel Packing Specifications

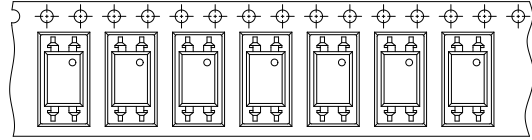
Option TD



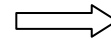
Direction of feed from reel



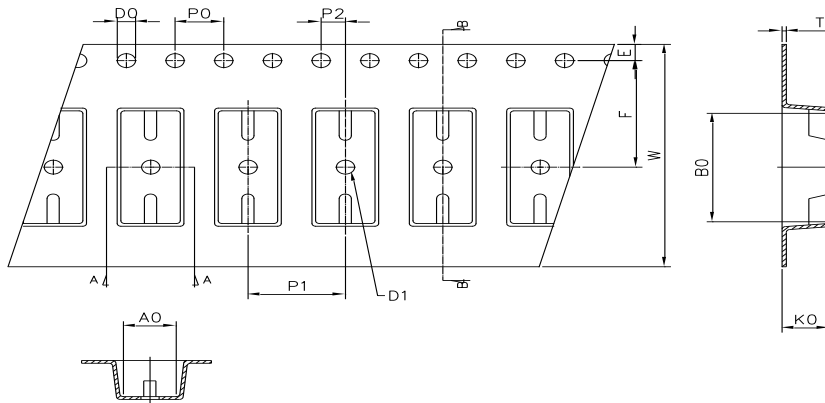
Option TU



Direction of feed from reel



Tape dimensions



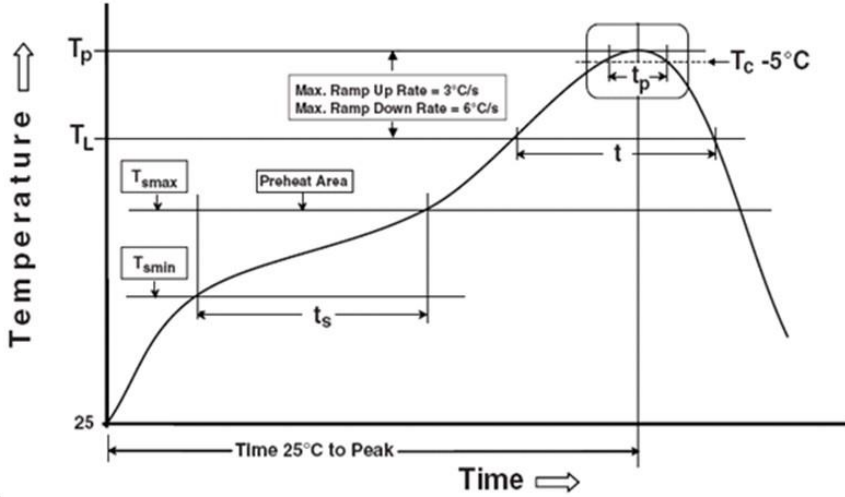
Dimension No.	Ao	Bo	Do	D1	E	F
Dimension (mm) S1	4.90±0.1	10.40±0.1	1.5±0.1	1.50±0.1	1.75±0.1	7.50±0.1
Dimension (mm) S2	4.88±0.1	12.55±0.1	1.5±0.1	1.50±0.1	1.75±0.1	11.5±0.1
Dimension No.	Po	P1	P2	t	W	Ko
Dimension (mm) S1	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	16.00±0.3	4.60±0.1
Dimension (mm) S2	4.00±0.1	8.00±0.1	2.00±0.1	0.40±0.1	24.00±0.3	4.00±0.1



Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200°C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5°C$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	3 times



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